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[Vishay/Siliconix](#)  
[DG3015DB-T2-E1](#)

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**DG3015**

Vishay Siliconix

## Low-Voltage, Low $R_{ON}$ , Dual DPDT Analog Switch

### DESCRIPTION

The DG3015 is a dual double-pole/double-throw monolithic CMOS analog switch designed for high performance switching of analog signals. Combining low power, high speed, low on-resistance and small physical size, the DG3015 is ideal for portable and battery powered applications requiring high performance and efficient use of board space.

The DG3015 is built on Vishay Siliconix's low voltage J12 process. An epitaxial layer prevents latchup. Break-before-make is guaranteed.

The switch conducts equally well in both directions when on, and blocks up to the power supply level when off.

### FEATURES

- Low Voltage Operation (2.7 V to 3.3 V)
- Low On-Resistance -  $R_{ON}$ : 0.8  $\Omega$
- 3 dB Loss at 100 MHz
- Fast Switching:  $t_{ON} = 40$  ns  
 $t_{OFF} = 35$  ns
- MICRO FOOT® Package
- Compliant to RoHS Directive 2002/95/EC



**RoHS**  
COMPLIANT

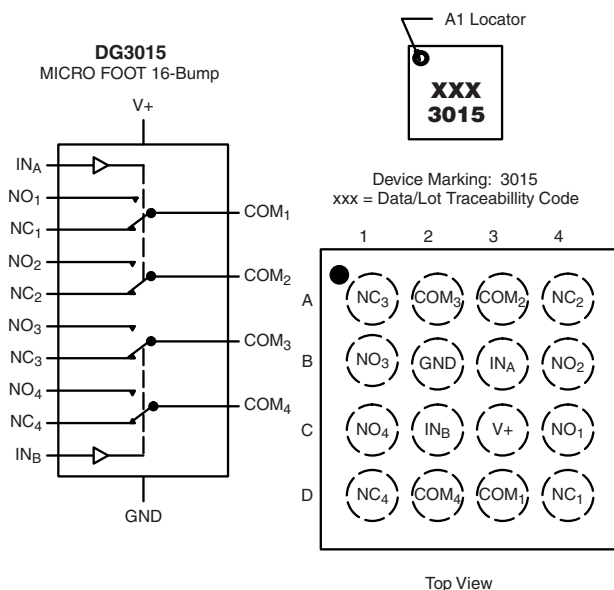
### BENEFITS

- Reduced Power Consumption
- High Accuracy
- Reduce Board Space
- TTL/1.8 V Logic Compatible
- High Bandwidth

### APPLICATIONS

- Cellular Phones
- Speaker Headset Switching
- Audio and Video Signal Routing
- PCMCIA Cards
- Battery Operated Systems

### FUNCTIONAL BLOCK DIAGRAM AND PIN CONFIGURATION



### TRUTH TABLE

Logic	NC1, 2, 3 and 4	NO1, 2, 3 and 4
0	ON	OFF
1	OFF	ON

### ORDERING INFORMATION

Temp Range	Package	Part Number
- 40 °C to 85 °C	MICRO FOOT: 16 Bump (4 x 4, 0.5 mm Pitch, 238 $\mu$ m Bump Height)	DG3015DB-T2-E1

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ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ , unless otherwise noted)			
Parameter	Limit	Unit	
Reference $V_+$ to GND	- 0.3 to + 6	V	
IN, COM, NC, NO <sup>a</sup>	- 0.3 to ( $V_+ + 0.3$ V)		
Current (Any terminal except NO, NC or COM)	30	mA	
Continuous Current (NO, NC or COM)	$\pm 150$		
Peak Current (Pulsed at 1 ms, 10 % duty cycle)	$\pm 250$		
Storage Temperature	(D Suffix)	$^\circ\text{C}$	
Package Solder Reflow Conditions <sup>b</sup>	IR/Convection		
Power Dissipation (Packages) <sup>c</sup>	MICRO FOOT: 16 Bump (4 x 4 mm) <sup>d</sup>	mW	

Notes:

- a. Signals on NC, NO, or COM or IN exceeding  $V_+$  will be clamped by internal diodes. Limit forward diode current to maximum current ratings.  
 b. Refer to IPC/JEDEC (J-STD-020B)  
 c. All bumps welded or soldered to PC Board.  
 d. Derate 9 mW/ $^\circ\text{C}$  above  $70^\circ\text{C}$ .

Permanent damage to the device may occur when the "Absolute Maximum Ratings" are exceeded. These stress ratings do not indicate conditions for which the device is intended to be functional. Functionality is only guaranteed to the conditions specified by the parametric table within the document.

SPECIFICATIONS (V+ = 3 V)							
Parameter	Symbol	Test Conditions Otherwise Unless Specified V+ = 3 V, ± 10 %,VIN = 0.4 V or 2 V <sup>e</sup>	Temp. <sup>a</sup>	Limits - 40 °C to 85 °C			Unit
				Min. <sup>b</sup>	Typ. <sup>c</sup>	Max. <sup>b</sup>	
Analog Switch							
Analog Signal Range <sup>d</sup>	VNO, VNC, VCOM		Full	0		V+	V
On-Resistance	RON	V+ = 2.7 V, VCOM = 0.2 V/1.5 V INO, INC = 100 mA	Room Full		0.80	1.2 1.3	Ω
RON Flatness	RON Flatness	V+ = 2.7 V, VCOM = 0 to V+, INO, INC = 100 mA	Room		0.16		
RON Match	ΔRON		Room		0.15		
Switch Off Leakage Current	INO(off) INC(off)	V+ = 3.3 V, VNO, VNC = 1 V/3 V, VCOM = 3 V/1 V	Room Full	- 2 - 20		2 20	nA
	ICOM(off)		Room Full	- 2 - 20		2 20	
	Channel-On Leakage Current		ICOM(on)	Room Full	- 2 - 20		
Digital Control							
Input High Voltage	VINH		Full	2			V
Input Low Voltage	VINL		Full			0.4	
Input Capacitance	Cin		Full		4		pF
Input Current	IINL or IINH	VIN = 0 or V+	Full	- 1		1	μA
Dynamic Characteristics							
Turn-On Time	tON	VNO or VNC = 2 V, RL = 300 Ω, CL = 35 pF	Room Full		40	65 67	ns
Turn-Off Time	tOFF		Room Full		35	60 62	
Break-Before-Make Time	td		Full	1	3		
Charge Injection <sup>d</sup>	QINJ	CL = 1 nF, VGEN = 0 V, RGEN = 0 Ω	Room		7		pC
Off-Isolation <sup>d</sup>	OIRR	RL = 50 Ω, CL = 5 pF, f = 1 MHz	Room		- 67		dB
Crosstalk <sup>d</sup>	XTALK		Room		- 70		
NO, NC Off Capacitance <sup>d</sup>	CNO(off) CNC(off)	VIN = 0 or V+, f = 1 MHz	Room		63		pF
	CNO(on) CNC(on)		Room		67		
Channel-On Capacitance <sup>d</sup>	CNO(on) CNC(on)		Room		200		
	CNO(on) CNC(on)		Room		196		



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SPECIFICATIONS (V+ = 3 V)							
Parameter	Symbol	Test Conditions Otherwise Unless Specified V+ = 3 V, ± 10 %,VIN = 0.4 V or 2 V <sup>e</sup>	Temp. <sup>a</sup>	Limits - 40 °C to 85 °C			Unit
				Min. <sup>b</sup>	Typ. <sup>c</sup>	Max. <sup>b</sup>	
Power Supply							
Power Supply Range	V+			2.7		3.3	V
Power Supply Current	I+	VIN = 0 or V+	Full			1	μA

Notes:

a. Room = 25 °C, full = as determined by the operating suffix.

b. Typical values are for design aid only, not guaranteed nor subject to production testing.

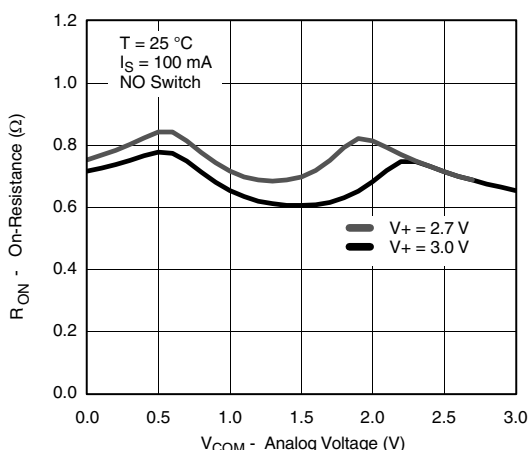
c. The algebraic convention whereby the most negative value is a minimum and the most positive a maximum, is used in this data sheet.

d. Guarantee by design, nor subjected to production test.

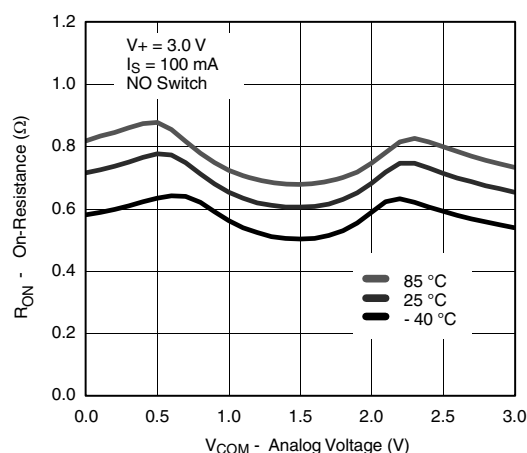
e. V<sub>IN</sub> = input voltage to perform proper function.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

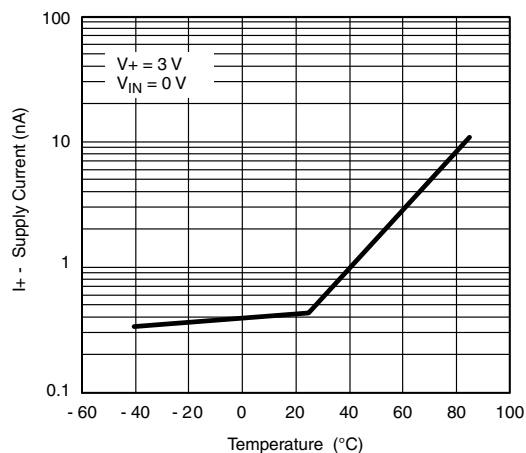
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



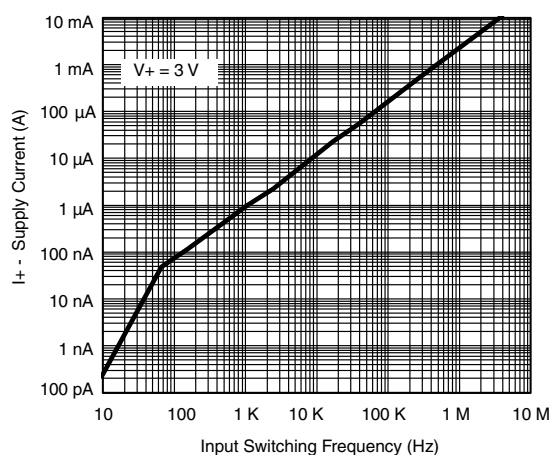
**R<sub>ON</sub> vs. V<sub>COM</sub> and Single Supply Voltage**



**R<sub>ON</sub> vs. Analog Voltage and Temperature**



**Supply Current vs. Temperature**



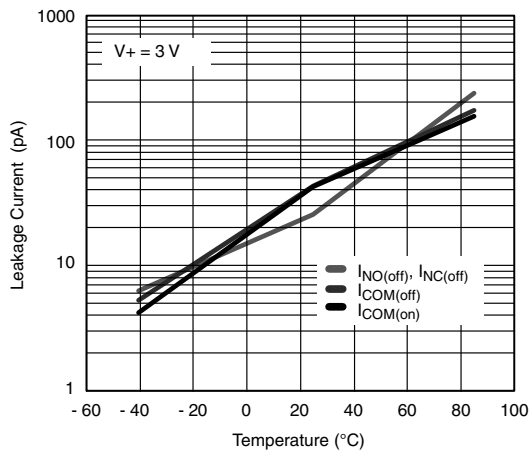
**Supply Current vs. Input Switching Frequency**

# DG3015

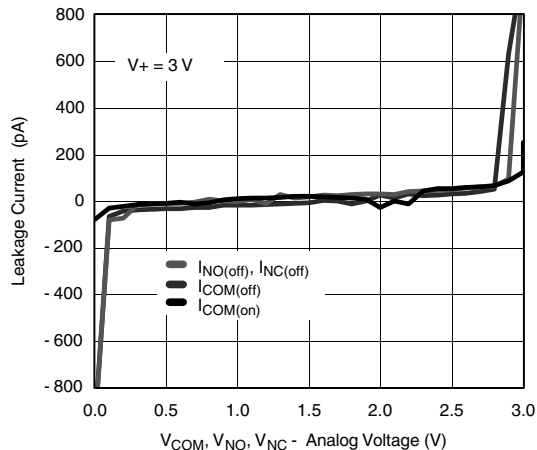
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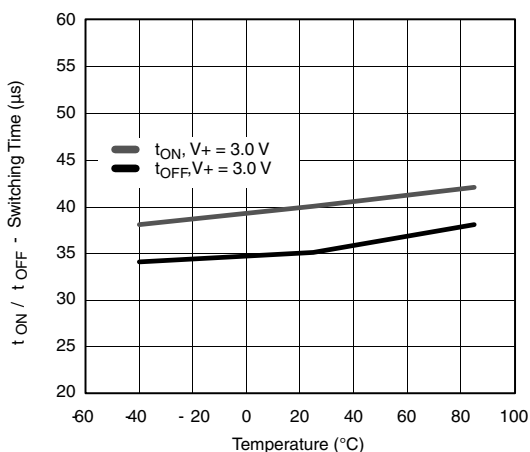
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



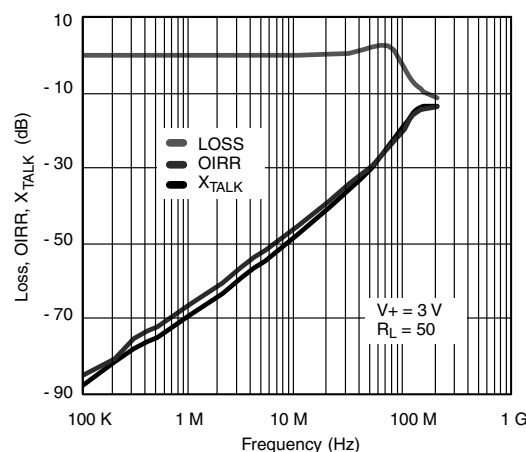
Leakage Current vs. Temperature



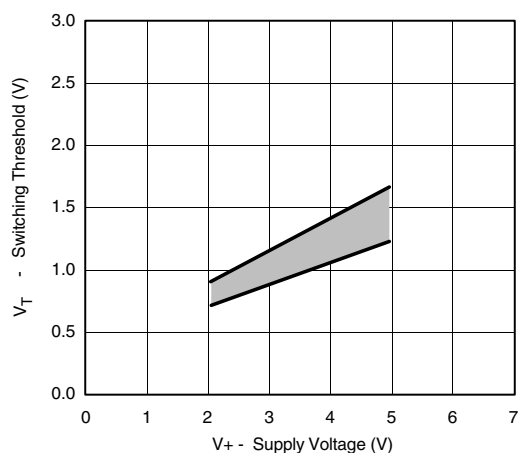
Leakage vs. Analog Voltage



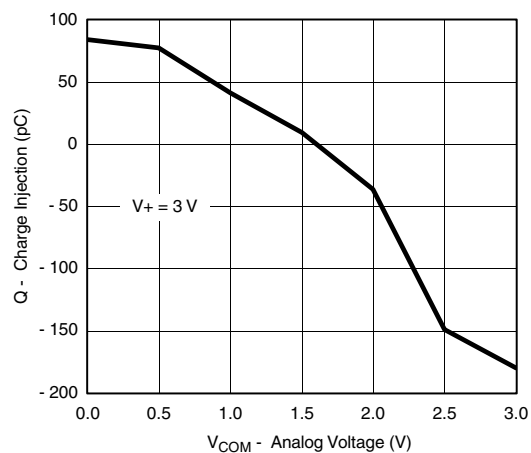
Switching Time vs. Temperature



Insertion Loss, Off-Isolation, Crosstalk vs. Frequency



Switching Threshold vs. Supply Voltage



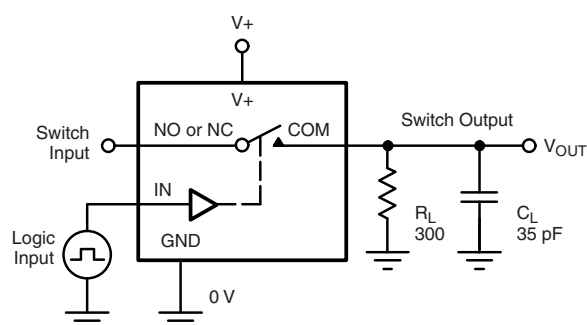
Charge Injection vs. Analog Voltage



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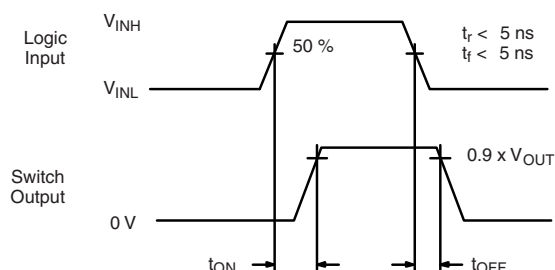
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## TEST CIRCUITS



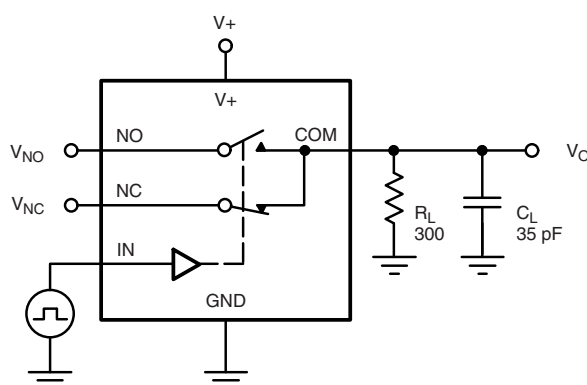
$C_L$  (includes fixture and stray capacitance)

$$V_{OUT} = V_{COM} \left( \frac{R_L}{R_L + R_{ON}} \right)$$

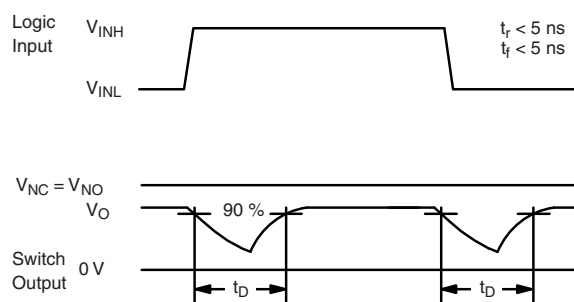


Logic "1" = Switch On  
Logic input waveforms inverted for switches that have the opposite logic sense.

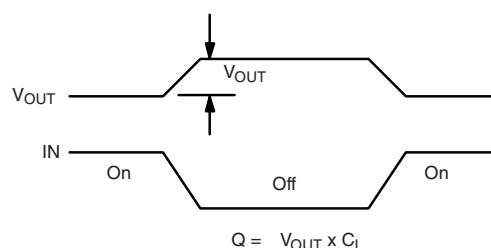
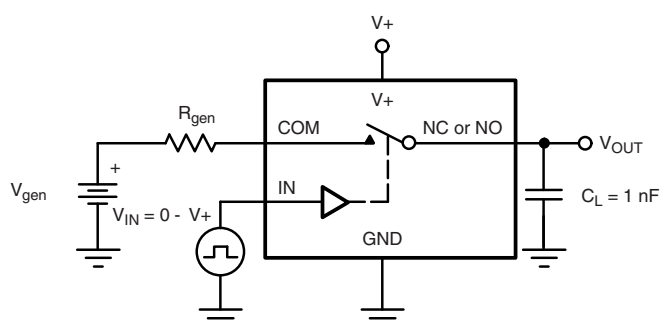
**Figure 1. Switching Time**



$C_L$  (includes fixture and stray capacitance)



**Figure 2. Break-Before-Make Interval**



IN depends on switch configuration: input polarity determined by sense of switch.

**Figure 3. Charge Injection**

## DG3015

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### TEST CIRCUITS

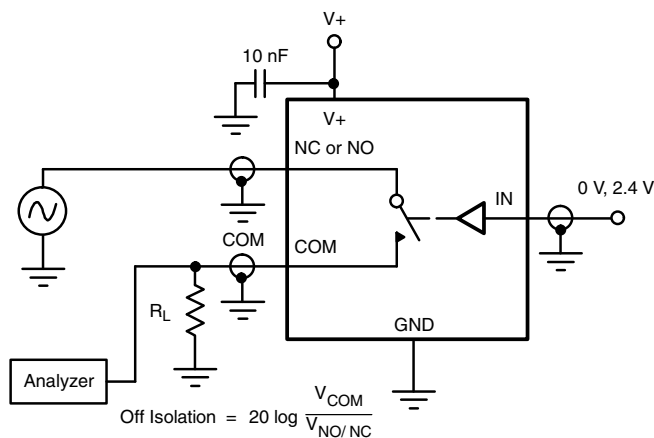


Figure 4. Off-Isolation

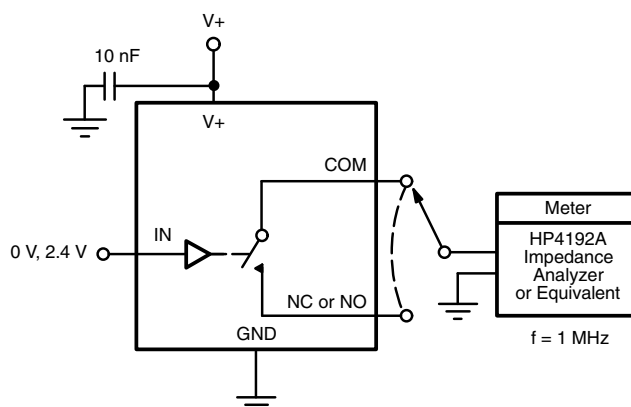


Figure 5. Channel Off/On Capacitance

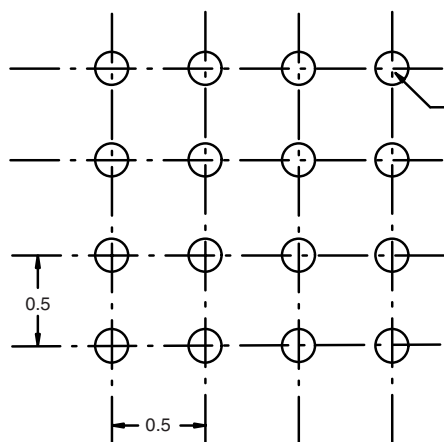


**DG3015**

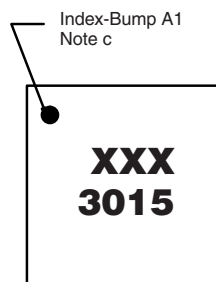
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**PACKAGE OUTLINE**

**MICRO FOOT: 16 BUMP (4 x 4, 0.5 mm PITCH, 0.238 mm BUMP HEIGHT)**

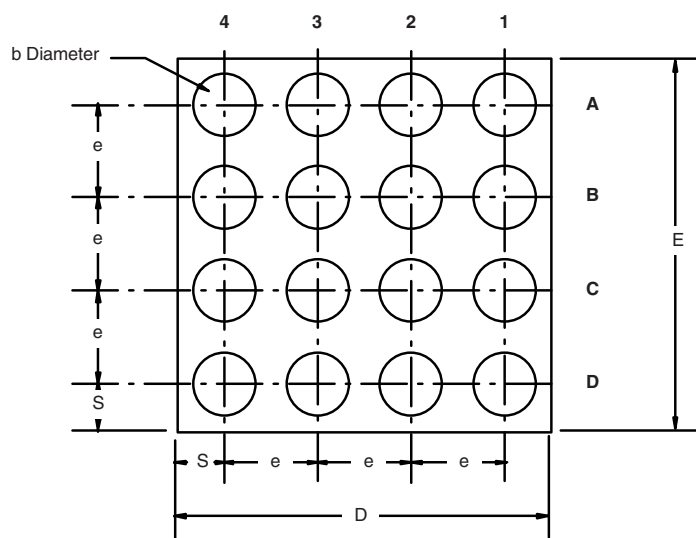
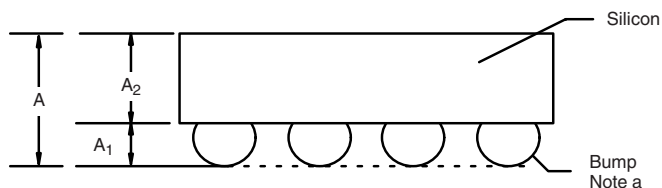


Recommended Land Pattern



Top Side (Die Back)

16 x  $\varnothing$  0.150 ~ 0.229  
Note b  
Solder Mask  $\varnothing$  ~ Pad Diameter + 0.1



Notes (Unless Otherwise Specified):

a. Bump is Lead (Pb)-free Sn/Ag/Cu.

b. Non-solder mask defined copper landing pad.

c. Laser Mark on silicon die back; back-lapped, no coating. Shown is not actual marking; sample only.

Dim.	Millimeters <sup>a</sup>		Inches	
	Min.	Max.	Min.	Max.
A	0.688	0.753	0.0271	0.0296
A <sub>1</sub>	0.218	0.258	0.0086	0.0102
A <sub>2</sub>	0.470	0.495	0.0185	0.0195
b	0.306	0.346	0.0120	0.0136
D	1.980	2.020	0.0780	0.0795
E	1.980	2.020	0.0780	0.0795
e	0.5 BASIC		0.0197 BASIC	
S	0.230	0.270	0.0091	0.0106

Notes:

a. Use millimeters as the primary measurement.

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see [www.vishay.com/ppg?72962](http://www.vishay.com/ppg?72962).

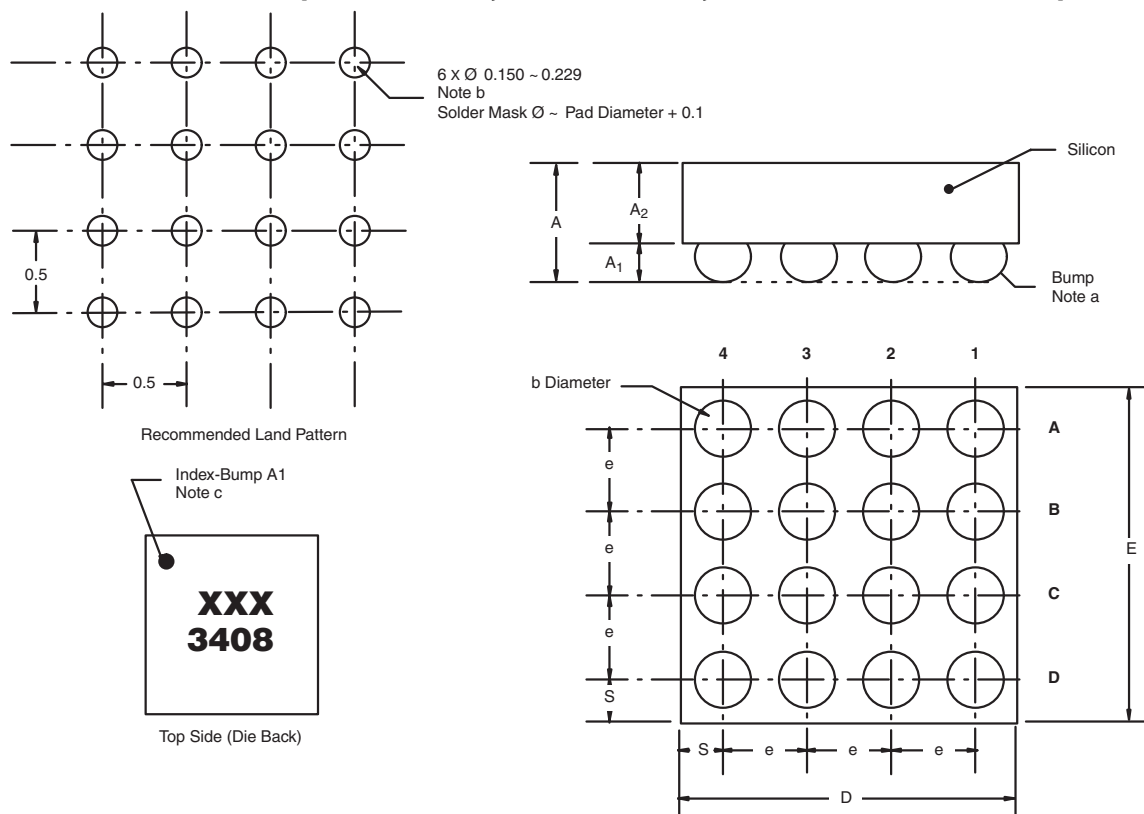




## Package Information

Vishay Siliconix

### MICRO FOOT: 16-BUMP (4 mm x 4 mm, 0.5 mm PITCH, 0.238 mm BUMP HEIGHT)



#### Notes

(unless otherwise specified)

a. Bump is lead (Pb)-free Sn/Ag/Cu.

b. Non-solder mask defined copper landing pad.

c. Laser mark on silicon die back; back-lapped, no coating. Shown is not actual marking; sample only.

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ECN: S11-1065-Rev. A, 13-Jun-11  
DWG: 6000



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